



Q,

#### COMPLEMENTARY PAIR ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

### **Features**

- Low On-Resistance
- Low Gate Threshold Voltage V<sub>GS(TH)</sub> < 1V</li>
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- ESD Protected Gate
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at https://www.diodes.com/products/automotive/automotive-

https://www.diodes.com/products/automotive/automotiveproducts/.

This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/guality/product-definitions/

### **Mechanical Data**

- Package: SOT563
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 3
- Weight: 0.006 grams (Approximate)

ESD Protected Top View Bottom View Top View Internal Schematic

SOT563

# Ordering Information (Note 4)

Part Number	Package	Pac	Packing			
Part Nulliber	Раскауе	Qty.	Carrier			
DMC2004VK-7	SOT563	3000	Tape & Reel			

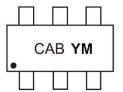
Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**



 $\begin{array}{l} \mathsf{CAB} = \mathsf{Product Type Marking Code} \\ \mathsf{YM} = \mathsf{Date Code Marking} \\ \mathsf{Y} = \mathsf{Year} \ (\mathsf{ex: J} = 2022) \\ \mathsf{M} = \mathsf{Month} \ (\mathsf{ex: 9} = \mathsf{September}) \end{array}$ 

#### Date Code Key

Year	2007		2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	U		J	K	L	М	Ν	0	Р	R	S	Т
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	-	0	0	4	<b>_</b>	0	7			0	Ν	D

# Maximum Ratings N-CHANNEL – Q1 (@TA = +25°C, unless otherwise specified.)

	Characteristic	Symbol	Value	Unit
Drain Source Voltage		VDSS	20	V
Gate-Source Voltage		VGSS	±8	V
Drain Current (Note 5)	TA = +25°C TA = +85°C	In	670 480	mA

# Maximum Ratings P-CHANNEL - Q2 (@TA = +25°C, unless otherwise specified.)

	Characteristic		Symbol	Value	Unit
Drain Source Voltage			VDSS	-20	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
Drain Current (Note 5)		TA = +25°C TA = +85°C	lo	-530 -380	mA

### **Thermal Characteristics**

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)		PD	0.45	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	281	°C/W
memai resistance, suiction to Ambient (Note 5)	t < 10s	RθJA	210	°C/W
Total Power Dissipation (Note 6)		PD	1	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Dave	129	°C/W
Thermal Resistance, Junction to Ambient (Note 0)	t < 10s	RθJA	97	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Notes:5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.



# Electrical Characteristics N-CHANNEL – Q1 (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)		•				
Drain-Source Breakdown Voltage	BVDSS	20	—	_	V	$V_{GS} = 0V$ , $I_D = 10\mu A$
Zero Gate Voltage Drain Current	IDSS	—	—	1.0	μΑ	$V_{DS} = 16V, V_{GS} = 0V$
Gate-Source Leakage	Igss	—	—	±1.0	μA	$V_{GS} = \pm 4.5 V$ , $V_{DS} = 0 V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.5	_	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$
		_	0.4	0.55		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 540mA
Static Drain-Source On-Resistance	RDS(ON)	—	0.5	0.70	Ω	VGS = 2.5V, ID = 500mA
		—	0.7	0.90		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 350mA
Forward Transfer Admittance (Note 8)	Y <sub>fs</sub>	200	—	-	mS	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.2A
Diode Forward Voltage	V <sub>SD</sub>	0.5	—	1.2	V	Vgs = 0V, Is = 115mA
DYNAMIC CHARACTERISTICS						
Input Capacitance	Ciss	—	—	150	pF	
Output Capacitance	Coss	—	—	25	pF	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V f = 1.0MHz
Reverse Transfer Capacitance	Crss	_		20	pF	

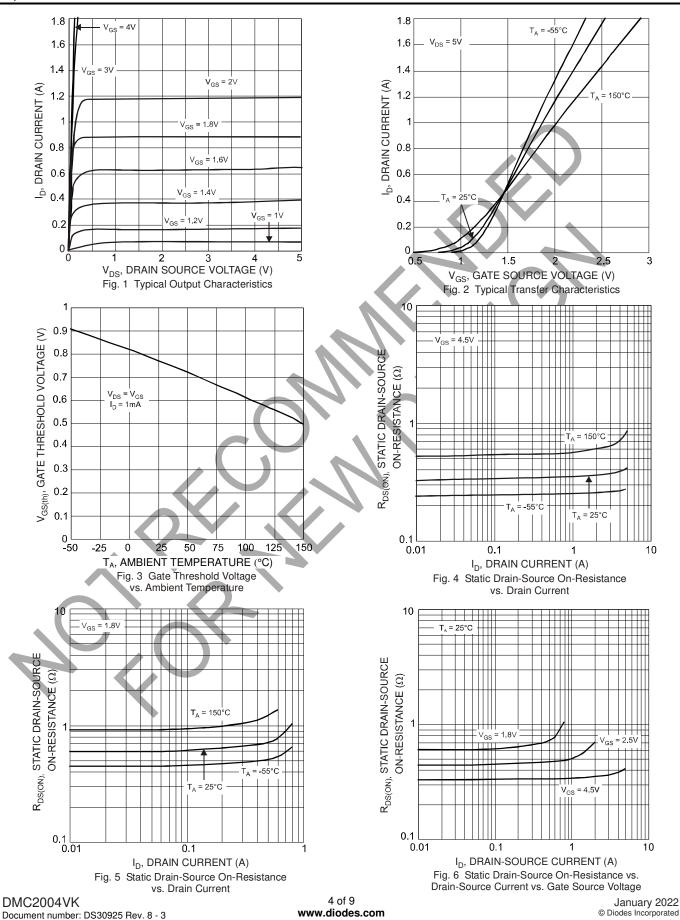
# Electrical Characteristics P-CHANNEL - Q2 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BVDSS	-20	-		V	$V_{GS} = 0V, I_D = -250 \mu A$
Zero Gate Voltage Drain Current	IDSS		-	-1.0	μA	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	Igss			±1.0	μA	$V_{GS} = \pm 4.5 V$ , $V_{DS} = 0 V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	Vgs(th)	-0.5	-/	-1.0	V	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$
Static Drain-Source On-Resistance	Rds(on)		0.7 1.1 1.7	0.9 1.4 2.0	Ω	$V_{GS} = -4.5V, I_D = -430mA \\ V_{GS} = -2.5V, I_D = -300mA \\ V_{GS} = -1.8V, I_D = -150mA$
Forward Transfer Admittance	Y <sub>fs</sub>	200	—	_	mS	$V_{DS} = 10V, I_D = 0.2A$
Diode Forward Voltage	Vsd	-0.5	—	-1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	_	175	pF	
Output Capacitance	Coss	_	—	30	pF	VDS = -16V, VGS = 0V f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	—	20	pF	

 Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing. Notes:



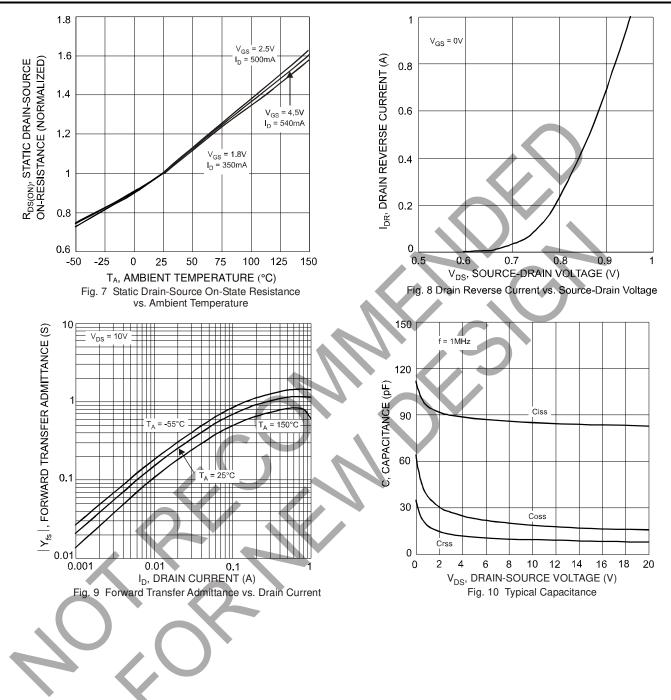
# **Q1, N-CHANNEL**



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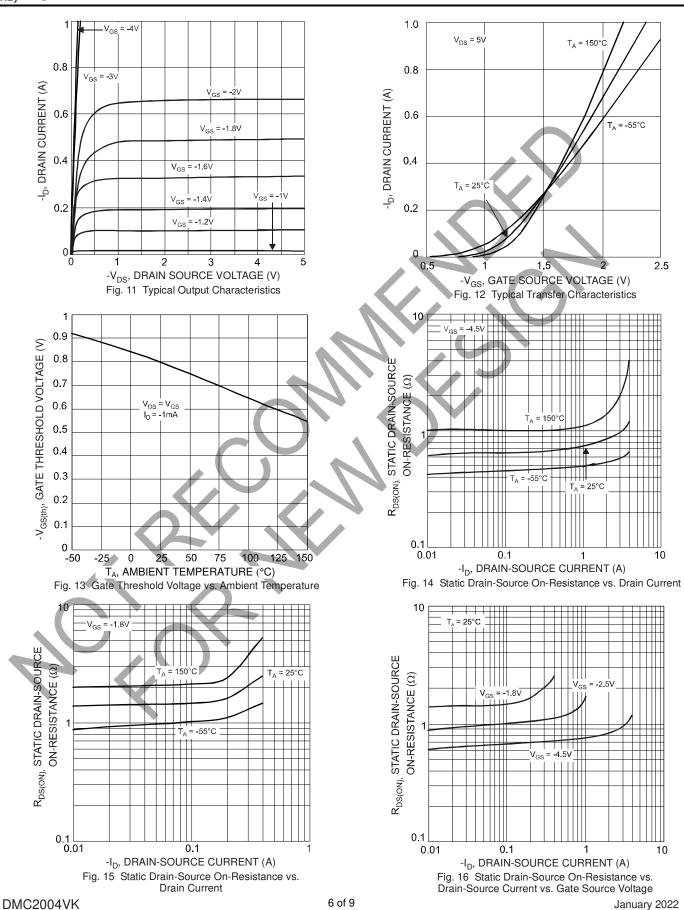


### Q1, N-CHANNEL (Continued)





# Q2, P-CHANNEL

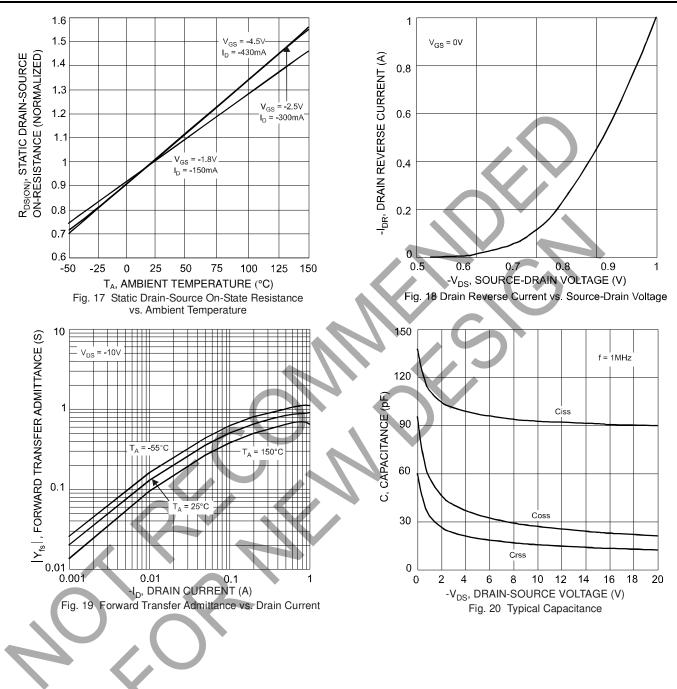




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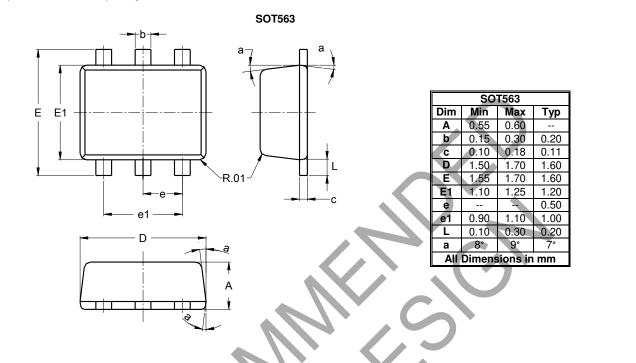
# Q2, P-CHANNEL (Continued)





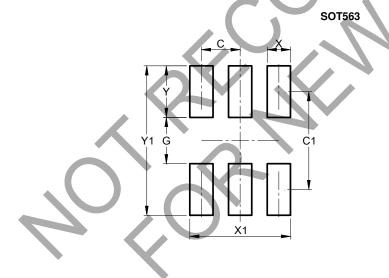
### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.500
C1	1.270
G	0.600
Х	0.300
X1	1.300
Y	0.670
Y1	1.940



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